## / Revised record

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## / Descriptions

Schottky Barrier Diode in a TO-263 Plastic Package.

## / Features

Low power loss, high efficiency.

## / Applications

## / Equivalent Circuit

## / Pinning




PIN1 Anode PIN 2 4 Cathode PIN 3 Anode

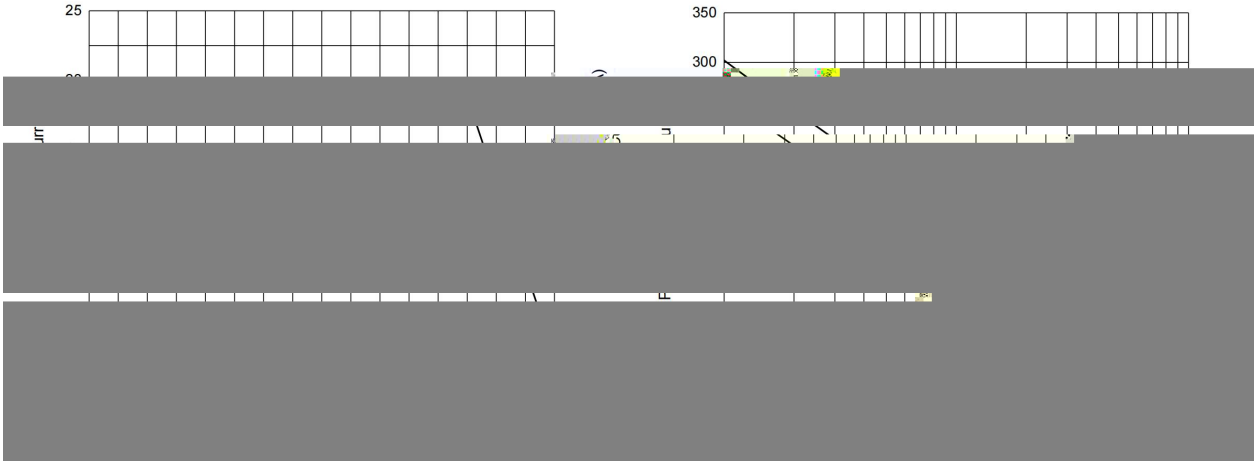
## / $h_{FE}$ Classifications & Marking

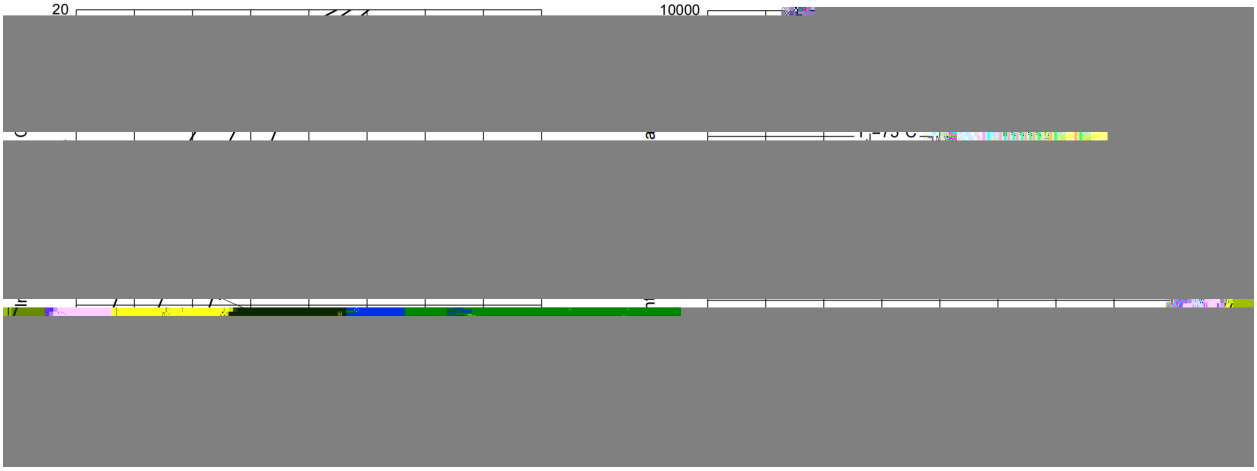
See Marking Instructions.

# MBRB2045

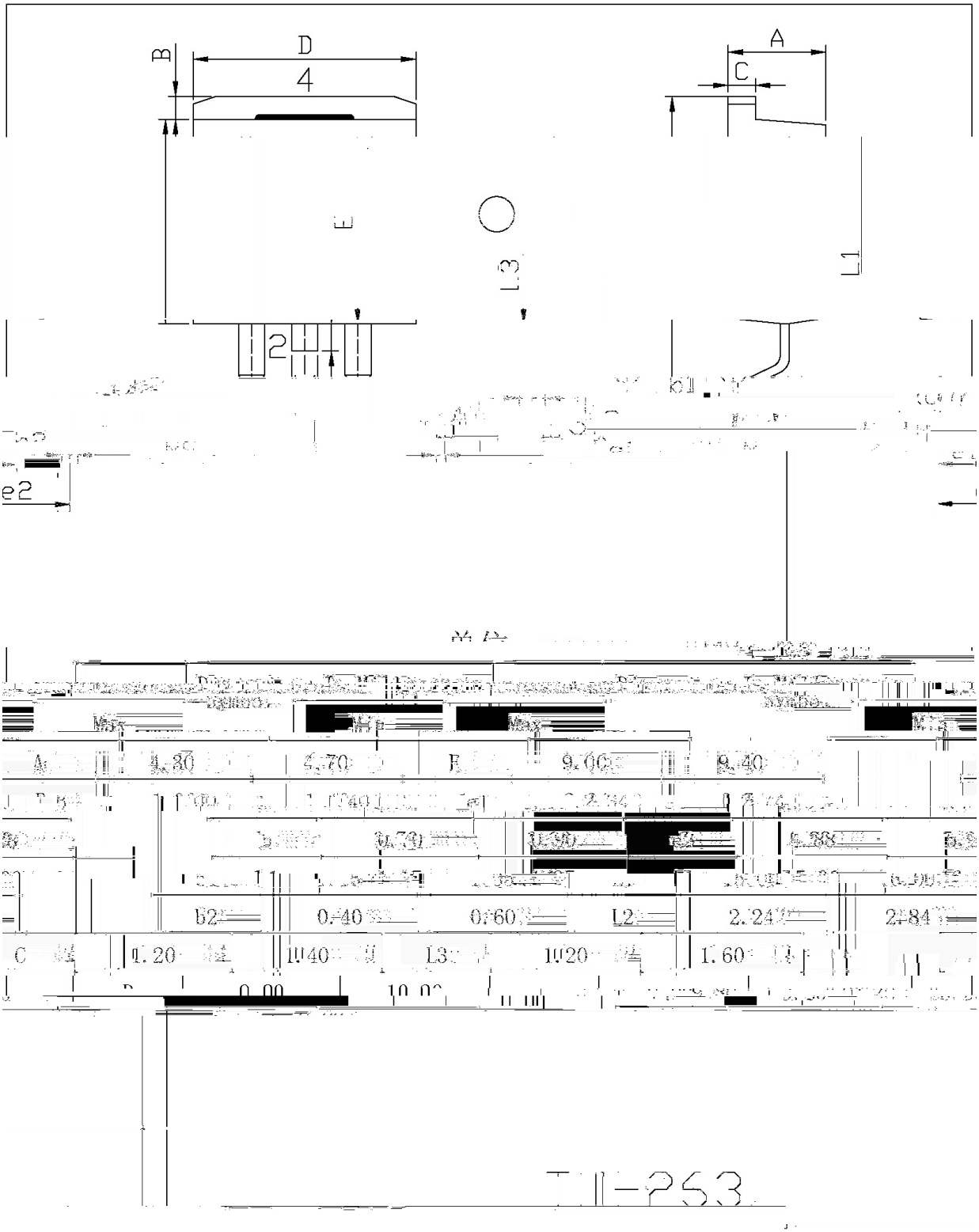
Rev. A May.-2021

## / Electrical Characteristic Curve

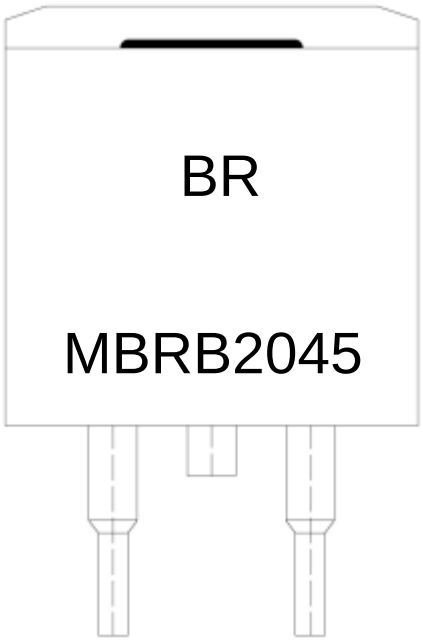


## / Package Dimensions



## / Marking Instructions




BR

MBRB2045

****

Note:

| | |
|---|---|
| BR: | Company Code |
| MBRB2045 | Product Type Code. |
| ****: | Lot No. Code, code change with Lot No. |

## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



| | | | | |
|---|---|---|---|---|
| | | | | Note: |
| 1 | 150 | 180 | 60 90sec; | 1.Preheating:150~180℃, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5℃, Duration:5±0.5sec. |
| 3 | | 2 | 10℃/sec. | 3. Cooling Speed: 2~10℃/sec. |

## / Resistance to Soldering Heat Test Conditions

| | | | |
|---|---|---|---|
| 260±5℃ | 10±1 sec. | Temp.:260±5℃ | Time:10±1 sec |

## / Packaging SPEC.

/ TUBE

| Package Type | Units | Dimension | (unit mm$^3$) |
|---|---|---|---|